PCN Number:	20200128000	PCN Date:	Jan. 29, 2020			
Title: Datasheet for TMP107						
Customer Contact:	PCN Manager		De	pt: (Quality Services	
Change Type:						
Assembly Site		Design		Wafer B	ump Site	
Assembly Process		Data Sheet		Wafer B	ump Material	
Assembly Material		Part number change			ump Process	
Mechanical Specifi		est Site		Wafer F		
Packing/Shipping/	Labeling T	est Process			ab Materials	
				Wafer F	ab Process	
Notification Details						
Description of Change:						
Texas Instruments Incorporated is announcing an information only notification.						
The product datasheet(s) is being updated as summarized below. The following change history provides further details.						
	listory provides tu	rther details.				
Texas Instruments					TMP107	
 INSTRUMENTS 			SBOS	716D – MAY 20	15-REVISED JANUARY 2020	
Changes from Revision C (October 2018) to Revision D Page						
Added footnote for biased operation up to 150°C						
Added looking of blased operation up to 100 0						
The datasheet number will be changing.						
Device Family		Change From:		Change 1	Го:	
TMP107		SBOS716C		SBOS716D		
These changes may be reviewed at the datasheet links provided.						
http://www.ti.com/product/TMP107						
Reason for Change:						
To accurately reflect device characteristics.						
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):						
No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.						
Changes to product identification resulting from this PCN:						
None.						
Product Affected:						
TMP107BID	TMP107BIDR					
For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.						

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com